

ABSTRACT

The purpose of the present invention is to provide an electroconductive adhesive composition having excellent thermal conductivity and migration resistance. The present invention relates to an electroconductive adhesive composition containing an electroconductive filler (A) including silver powder (a1) and silver-coated copper powder (a2), and a binder composition (B), wherein the electroconductive adhesive composition contains 3-65% by mass of the silver-coated copper powder (a2) with respect to the entire amount of the electroconductive filler (A), and contains 95-99.95% by mass of the electroconductive filler (A) with respect to the total quantity of nonvolatile components in the electroconductive adhesive composition.